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IN THE CLAIMS:

Please amend the claims, as follows:

1. (Previously presented) A surface acoustic wave (SAW) filter device with a chip substrate of a piezoelectric material, comprising:

a plurality of interdigital transducers accommodated in a plastic package;

a terminal member connected to said plastic package, wherein said terminal member comprises a lateral extending portion recessed into said package which contacts the back surface of the chip substrate,

wherein common potential means for providing a common potential in the interdigital transducers, charge neutralizing means for neutralizing charge generated on the chip substrate due to polarization, or charge escape means for causing escape of charge generated on the chip substrate due to polarization, is provided as electric discharge preventing means for preventing electric discharge among the plurality of interdigital transducers on the chip substrate.

2. (Currently amended) The SAW filter device according to claim 1, wherein the electric discharge preventing means ~~is realized by~~ comprises a high resistivity thin film provided between the chip substrate and the interdigital transducers and covering the front surface of the chip substrate.

3. (Currently amended) The SAW filter device according to claim 1, wherein the electric discharge preventing means ~~is realized by~~ comprises a high resistivity thin film formed such as

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to cover the entire interdigital transducer.

4. (Currently amended) The SAW filter device according to claim 1, which further comprises a film of a conductive material covering the front surface of the chip substrate and the interdigital transducers.
5. (Currently amended) The SAW filter device according to claim 1, wherein the electric discharge preventing means ~~is realized by~~ comprises opposed portions of the interdigital transducers having non-sharp shapes.
6. (Currently amended) The SAW filter device according to claim 1, wherein the electric discharge preventing means ~~is realized by~~ comprises a film of a conductive material provided on the front surface side edge portion of the chip substrate.
7. (Currently amended) The SAW filter device according to claim 1, wherein the electric discharge prevention means ~~is realized by~~ comprises a high resistivity pattern provided so as to surround the front surface center portion of the chip substrate.
8. (Currently amended) A surface acoustic wave (SAW) filter device with a chip substrate of a piezoelectric material, comprising:
 - a plurality of interdigital transducers and accommodated in a plastic package,
 - wherein said plastic package comprises a terminal member ~~made of~~ comprises metal extending out of the package and extending into the package such as to form an L-shaped

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portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion,

wherein a first pattern as an extension of part of the interdigital transducers, a second pattern spaced apart from the first pattern and a dummy electrode pattern connected to the second pattern are formed on the front surface of the chip substrate as an electric discharge preventing means for preventing electric discharge among the plurality of interdigital electric patterns.

9. (Currently amended) An SAW filter device ~~with~~ comprising:

a chip substrate of a piezoelectric material having a plurality of interdigital transducers and accommodated in a plastic ~~package~~, package; and

~~wherein~~ an electric discharge preventing means for preventing electric discharge among the plurality of interdigital electric patterns, wherein said electric discharge preventing means includes ~~is realized by~~ opposed portions of the interdigital transducers having non-sharp shapes.

10. (Currently amended) A package for accommodating a surface acoustic wave (SAW) filter formed on the front surface of a chip substrate, said package comprising:

a plastic molding formed having a front surface, a back surface, an edge wall, and a central recess for receiving said SAW filter; and

a plurality of terminals extending out of the package and extending into the package,

wherein one of said terminals comprises an L-shaped ~~portion~~, and portion ~~and wherein~~ the back surface of said chip substrate contacts said L-shaped portion.

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11. (Previously presented) A surface acoustic wave (SAW) filter device with a chip substrate of a piezoelectric material, comprising:

a plurality of interdigital transducers and accommodated in a plastic package, said plastic package comprising a terminal member made of metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic such that the back surface of the chip substrate is in contact with the L-shaped portion,

wherein common potential means for providing a common potential in the interdigital transducers, charge neutralizing means for neutralizing charge generated on the chip substrate due to polarization, or charge escape means for causing escape of charge generated on the chip substrate due to polarization, is provided as electric discharge preventing means for preventing electric discharge among the plurality of interdigital transducers on the chip substrate.

12. (Previously presented) The SAW filter device according to claim 11, wherein the back surface of the chip substrate is secured by a conductive adhesive to the package.

13. (Currently amended) An SAW filter device including an SAW filter according to claim 2, which comprises a plastic package including a terminal member ~~made of~~ comprising metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

14. (Currently amended) An SAW filter device including an SAW filter according to claim 3,

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which comprises a plastic package including a terminal member ~~made of~~ comprising metal extending out of the package and extending into the package such as to form an L-shaped portion, the clip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shape portion.

15. (Currently amended) An SAW filter device including an SAW filter according to claim 4, which comprises a plastic package including a terminal member ~~made of~~ comprising metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

16. (Currently amended) An SAW filter device including an SAW filter according to claim 5, which comprises a plastic package including a terminal member ~~made of~~ comprising metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

17. (Currently amended) An SAW filter device including an SAW filter according to claim 6, which comprises a plastic package including a terminal member ~~made of~~ comprising metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shape portion.

18. (Currently amended) An SAW filter device including an SAW filter according to claim 7,

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which comprises a plastic package including a terminal member ~~made of~~ comprising metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

19. (Currently amended) An SAW filter device including an SAW filter according to claim 8, which comprises a plastic package including a terminal member ~~made of~~ comprising metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

20. (Currently amended) An SAW filter device including an SAW filter according to claim 9, which comprises a plastic package including a terminal member ~~made of~~ comprising metal extending out of the package and extending into the package such as to form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact is in contact with the L-shaped portion.

21. (Previously presented) A surface acoustic wave (SAW) device, comprising:

- a chip substrate having a front surface and a back surface and formed from a piezoelectric material;

- a plurality of interdigital transducers formed on the front surface of said chip substrate;

- a high resistivity thin film provided between the chip substrate and the interdigital transducers, wherein said high resistivity film prevents electric discharge among the plurality of interdigital transducers on the chip substrate;

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a plastic package receiving said SAW filter; and
a plurality of terminal members connected to said plastic package,
wherein one of said terminal members comprises a lateral extending portion recessed
into said package which contacts the back surface of said chip substrate.

22. (Previously presented) The SAW device according to claim 21, wherein said high resistivity thin film substantially covers the entire interdigital transducer.

23. (Previously presented) The SAW device according to claim 21, further comprising:
a conductive material film covering the front surface of the chip substrate and the interdigital transducers.

24. (Previously presented) The SAW device according to claim 21, wherein said high resistivity film substantially covers the front surface of said chip substrate.

25. (Previously presented) The SAW device according to claim 21, wherein said high resistivity film surrounds the front surface center portion of the chip substrate.

26. (Previously presented) The SAW device according to claim 21, further comprising:
a conductive material film covering the front surface of the chip substrate and the interdigital transducers.

27. (Previously presented) The SAW device according to claim 21, wherein said one of said terminal members comprises a plate extending out of the package and into the package to

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form an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

28. (Previously presented) The SAW device according to claim 22, further comprising:

a terminal member extending out of the package and extending into the package, thereby forming an L-shaped portion, the chip substrate being accommodated in the plastic package such that the back surface of the chip substrate is in contact with the L-shaped portion.

29. (Previously presented) The package for accommodating an SAW filter of claim 10, wherein said terminal comprising said L-shaped portion comprises a ground terminal.

30. (Currently amended) The package for accommodating an SAW filter of claim 10,

wherein said terminal comprising said L-shaped portion comprises a longitudinal portion extending out of said package and a lateral portion extending into said central ~~rectangular~~ recess, said central recess being rectangular,

wherein said lateral portion extends into said recess to create a contact with said chip substrate.

31. (Previously presented) The SAW filter device of claim 1, wherein said terminal member comprises an L-shaped portion.

32. (Previously presented) The SAW filter device of claim 31, wherein the back surface of the chip substrate contacts the L-shaped portion.